

● **General Description**

The TF070N06N combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

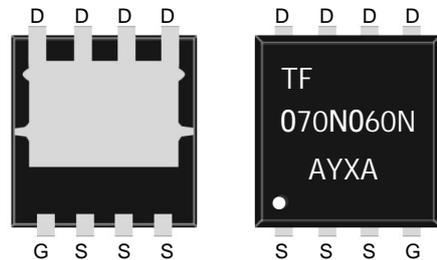
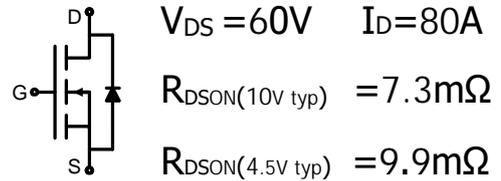
● **Features**

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

● **Application**

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

● **Product Summary**



**PDFNWB5x6-8L**

● **Ordering Information:**

Part NO.	TF070N06N
Marking 1	070N06N:TF070N06N
Marking 2	TF:tuofeng; Y:year code; X:Week; AA:device code;
MOQ	5000 PCS

● **Absolute Maximum Ratings** ( $T_C = 25^\circ\text{C}$ )

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D @ T_C = 25^\circ\text{C}$	80	A
	$I_D @ T_C = 75^\circ\text{C}$	56	A
	$I_D @ T_C = 100^\circ\text{C}$	48	A
Pulsed Drain Current ①	$I_{DM}$	210	A
Total Power Dissipation	$P_D @ T_C = 25^\circ\text{C}$	80	W
Total Power Dissipation	$P_D @ T_A = 25^\circ\text{C}$	2.0	W
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$

Note: ① Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$  ;



Shenzhen Tuofeng Semiconductor Technology Co., Ltd  
**N-CHANNEL ENHANCEMENT MODE POWER MOSFET**

**TF070N06N**

Single Pulse Avalanche Energy	$E_{AS}$	150			mJ	
Avalanche Current	$I_{AS} I_{AR}$	25			A	
<b>•Thermal resistance</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>	
Thermal resistance, junction - case	$R_{thJC}$	-	-	5.5	° C/W	
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	65	° C/W	
Soldering temperature, wave soldering for 8s	$T_{sold}$	-	-	265	° C	
<b>•Electronic Characteristics at <math>T_j=25</math> (unless otherwise specified)</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Condition</b>	<b>Min.</b>	<b>Typ</b>	<b>Max.</b>	<b>Unit</b>
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.0	1.5	2.3	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 58V, V_{GS} = 0V$			1.0	$\mu A$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 20A$		7.3	9.0	m $\Omega$
		$V_{GS} = 4.5V, I_D = 20A$		9.9	12	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 15V, I_D = 20A$		15		S
Source-drain voltage	$V_{SD}$	$I_S = 20A$			1.20	V
<b>•Electronic Characteristics</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Condition</b>	<b>Min.</b>	<b>Typ</b>	<b>Max.</b>	<b>Unit</b>
Input capacitance	$C_{iss}$	$V_{DS} = 25V, V_{GS} = 0V$ $f = 1MHz$	-	2000	-	pF
Output capacitance	$C_{oss}$		-	217	-	
Reverse transfer capacitance	$C_{rss}$		-	193	-	
<b>•Gate Charge characteristics (<math>T_a = 25^\circ C</math>)</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Condition</b>	<b>Min.</b>	<b>Typ</b>	<b>Max.</b>	<b>Unit</b>
Gate Resistance	$R_g$	$f = 1MHz$		1.5		$\Omega$
Total gate charge	$Q_g$	$V_{DD} = 25V$ $I_D = 20A$ $V_{GS} = 10V$	-	30	-	nC
Gate - Source charge	$Q_{gs}$		-	9.0	-	
Gate - Drain charge	$Q_{gd}$		-	15	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS} = 25V, V_{DS} = 10V$ $R_G = 1.8\Omega, I_D = 20A$		13		ns
Turn-ON Rise time	$t_r$			7.8		ns
Turn-Off Delay time	$t_{D(off)}$			35		ns
Turn-Off Fall time	$t_f$			15		ns

Fig.1 Power Dissipation

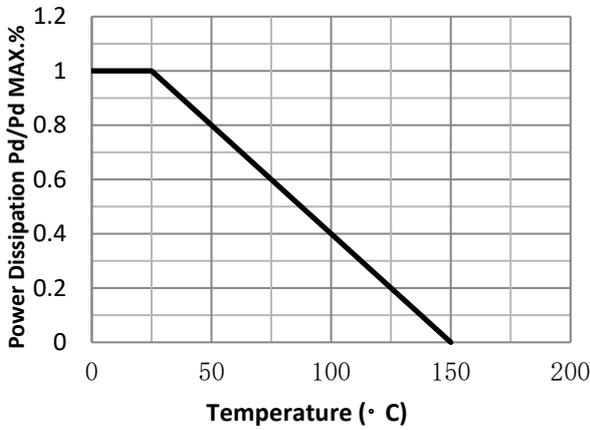


Fig.2 Typical output Characteristics

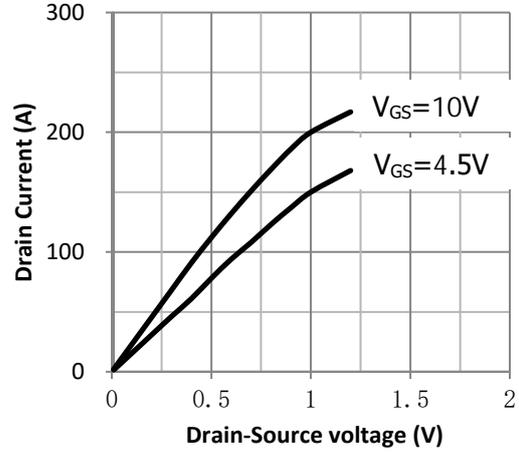


Fig.3 Threshold Voltage V.S Junction Temperature

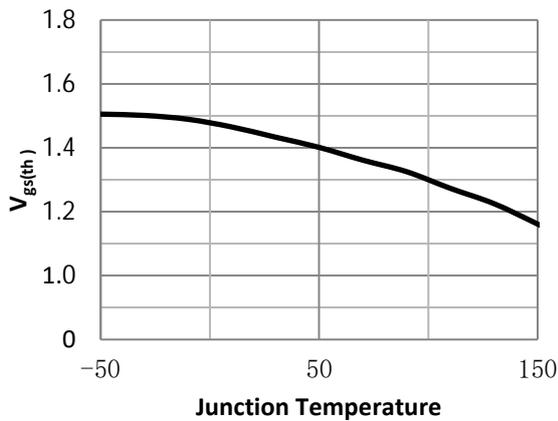


Fig.4 Resistance V.S Drain Current

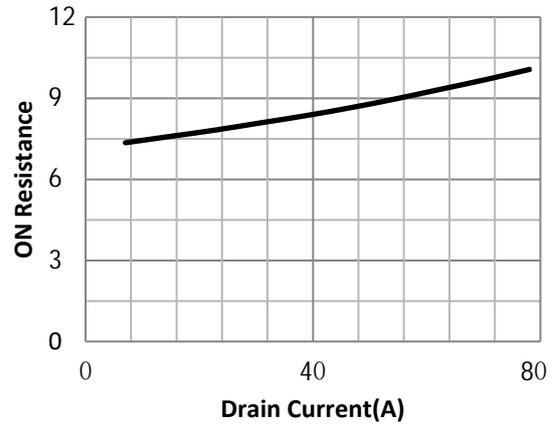


Fig.5 On-Resistance VS Drain Current

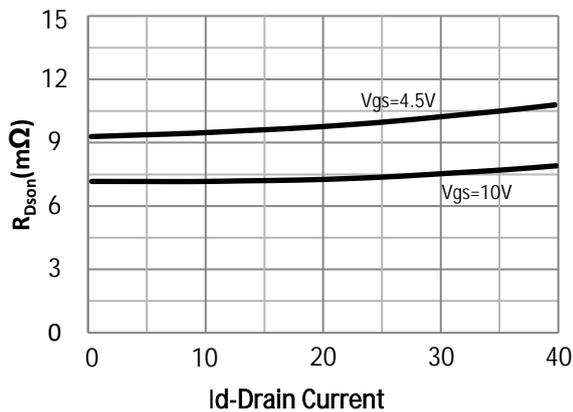


Fig.6 On-Resistance V.S Junction Temperature

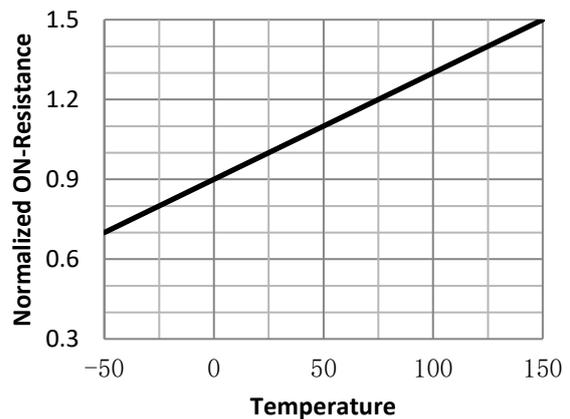


Fig.7 Switching Time Measurement Circuit

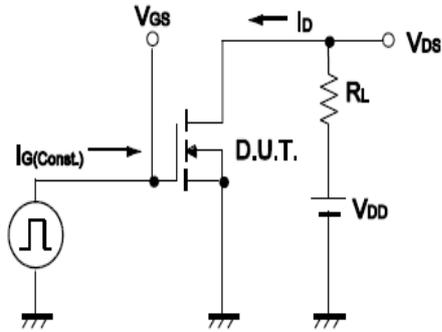


Fig.8 Gate Charge Waveform

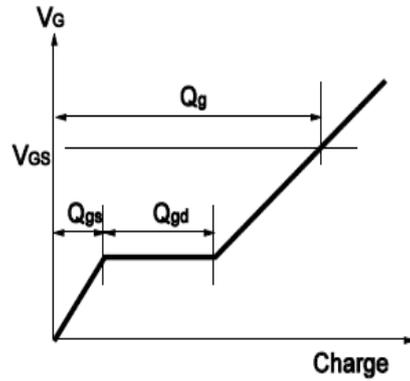


Fig.9 Switching Time Measurement Circuit

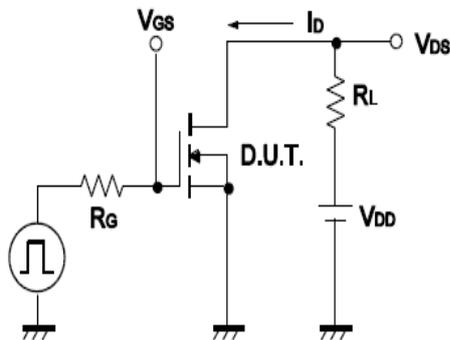


Fig.10 Gate Charge Waveform

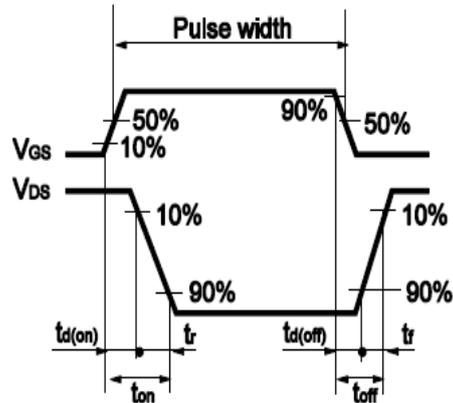


Fig.11 Avalanche Measurement Circuit

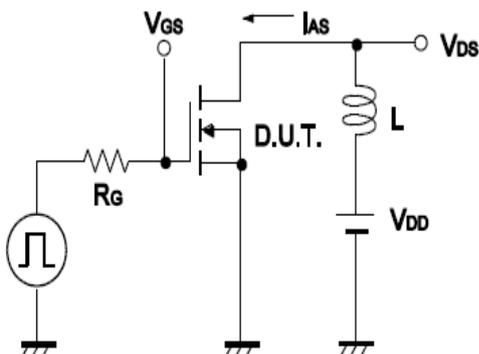
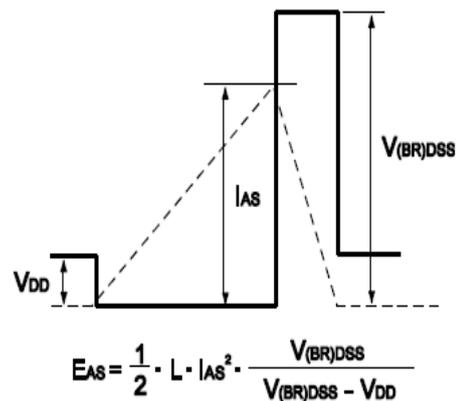
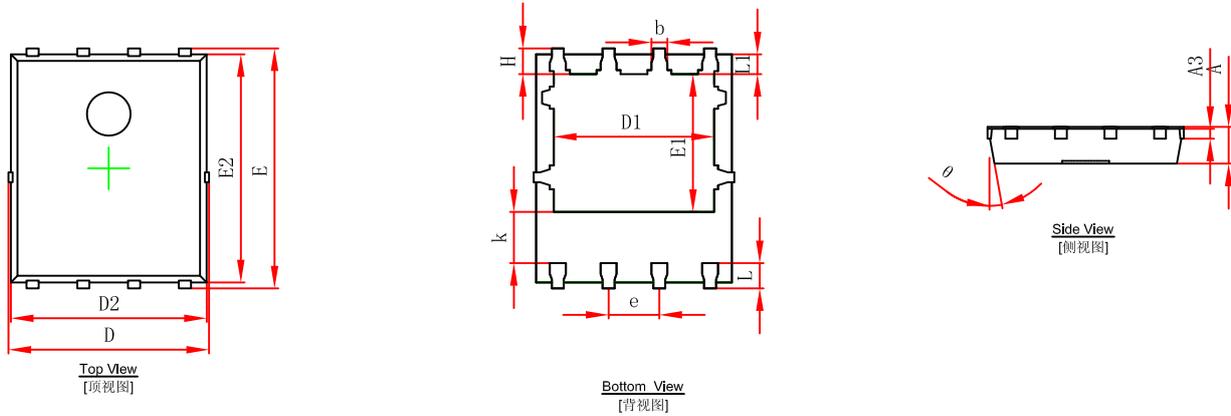


Fig.12 Avalanche Waveform

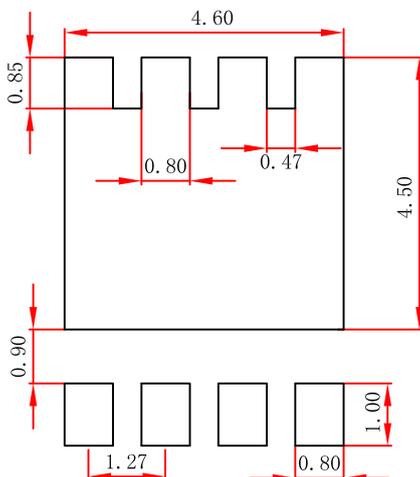


**PDFNWB5x6-8L Package Outline Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
$\theta$	10°	12°	10°	12°

**PDFNWB5x6-8L Suggested Pad Layout**



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance:  $\pm 0.05$ mm.  
 3. The pad layout is for reference purposes only.